

PCN# 20200109000.1
Qualification of DMOS6 as an additional Wafer Fab Site option for select devices
Change Notification / Sample Request

Date: January 16, 2020

Dear TI Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

The customer should acknowledge receipt of this notification by email within **30** days of the date of receipt. Lack of acknowledgement of this notice within 30 days constitutes customer acceptance of the change.

Samples or additional data to support customer evaluation must be requested within 30 days of receipt of this notification. If samples are requested for evaluation the customer must provide evaluation results within the sample evaluation period indicated on page 3 of this notification. The Sample Evaluation Period begins on the date the customer receives samples from TI.

If the customer approved the change TI can proceed with implementation of the change. The proposed first ship date is shown on page 3.

If the customer does not approve the PCN or the approval response is not provided within the Sample Evaluation Period, TI can implement the change, but the customer may elect to place an order for unchanged product by the Last Time Buy Date for delivery by the Last Time Ship Date. TI cannot guarantee that shipments to the customer after any last time order is delivered will not include the changed material. If the customer places an order with delivery after the Last Time Shipment Date, the order may be fulfilled with changed material or any material processed to TI specifications at that future time.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com). For sample requests or sample related questions, contact your field sales representative.

Sincerely,
PCN Team
SC Business Services

20200109000.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
CC2640R2FRHBR	39210398

Technical details of this Product Change follow on the next page(s).

PCN Number:	20200109000.1		PCN Date:	Jan 16, 2020	
Title:	Qualification of DMOS6 as an additional Wafer Fab Site option for select devices in F021 Technology				
Customer Contact:	PCN Manager		Dept:	Quality Services	
Proposed 1st Ship Date:	Apr 16, 2020	Sample Eval Period:	180 Days		
Last Time Buy Date:	Sep 16, 2020	Last Time Ship Date:	Dec 16, 2020		
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input checked="" type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		

PCN Details

Description of Change:

This change notification is to announce the addition of DMOS6 as an additional Wafer Fab site option for the products listed in the "Product Affected" section of this document.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
TSMC-F14	F021	300 mm	DMOS6	F65	300 mm

In support of the qualification of the DMOS6 Wafer Fab site, the flash design library was changed to allow production in the new fab site. The change does not impact device functionality, and device performance is accounted for in the respective datasheet specifications.

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
TSMC-F14	T14	TWN	Tainan City

New Fab Site

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
DMOS6	DM6	USA	Dallas

Sample product shipping label (not actual product label)

Product Affected Group:

CC2640R2FRHBR

Qualification Report

Approve Date 10-DEC-2019

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device #1: CC2640R2FRGZR	Qual Device #2: CC2640R2RSMR	Qual Device #3: CC2640R2FRGZR	Qual Device #4: CC2640R2FRHBR	Qual Device #5: CC2640R2FRSMR
HTOL	High Temp. Operating Life, 125C, 100K W/E cycle preconditioning	1000 Hours	3/231/0	-	-	-	-
HTSL	High Temp. Storage Bake, 150C, 100K W/E cycle preconditioning	1000 Hours	3/215/0	-	-	-	-
AC	Autoclave 121C	96 Hours	3/231/0	-	1/77/0	1/77/0	1/77/0
HAST	Biased HAST, 110C/85%RH	264 Hours	3/231/0	-	1/77/0	-	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	-	1/77/0	1/77/0	1/77/0
TC	Temperature Cycle, -55/125C	700 Cycles	3/231/0	1/77/0	1/77/0	1/77/0	1/77/0
CDM	ESD CDM	750 V	1/3/0	1/3/0	-	-	-
HBM	ESD HBM	2500 V	1/3/0	1/3/0	-	-	-
LU	Latch-up, High Temp	+/- 100 mA and 1.5 x Vmax @ max Tj	1/3/0	-	-	-	-

- QBS: Qual By Similarity

- Qual Devices CC2640R2FRGZR, CC2640R2FRHBR, and CC2640R2FRSMR are qualified at LEVEL3-260C.

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable.

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

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